

# FFB10UP20S Ultrafast Recovery Power Rectifier

### **Features**

• Ultrafast with Soft Recovery : < 45ns

• High Reverse Voltage : V<sub>RRM</sub> = 200V

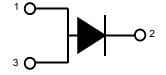
· Avalanche Energy Rated

Planar Construction

### **Applications**

- · Output Rectifiers
- · Switching Mode Power Supply
- · Free-wheeling diode for motor application
- · Power switching circuits





1. Anode 2. Cathode 3. Anode

### Absolute Maximum Ratings (per diode) T<sub>a</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>RRM</sub>	Peak Repetitive Reverse Voltage	200	V
V <sub>RWM</sub>	Working Peak Reverse Voltage	200	V
V <sub>R</sub>	DC Blocking Voltage	200	V
I <sub>F(AV)</sub>	Average Rectified Forward Current @ T <sub>C</sub> = 120°C	10	А
I <sub>FSM</sub>	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	100	Α
T <sub>J,</sub> T <sub>STG</sub>	Operating Junction and Storage Temperature	- 65 to +150	°C

### Thermal Characteristics T<sub>a</sub> = 25°C unless otherwise noted

Symbol	Parameter	Max	Units
$R_{\theta,JC}$	Maximum Thermal Resistance, Junction to Case	3.0	°C/W

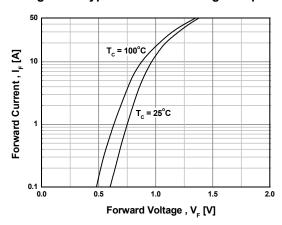
### Electrical Characteristics (per diode) T<sub>a</sub> = 25°C unless otherwise noted

Symbol	Parameter		Min.	Тур.	Max.	Units
V <sub>FM</sub> *	I <sub>F</sub> = 10A I <sub>F</sub> = 10A	T <sub>C</sub> = 25 °C T <sub>C</sub> = 150 °C			1.15 1.0	V V
I <sub>RM</sub> *	V <sub>R</sub> = 200V V <sub>R</sub> = 200V	T <sub>C</sub> = 25 °C T <sub>C</sub> = 150 °C	-	-	100 500	μA μA
t <sub>rr</sub>	$I_F$ =1A, di/dt = 100A/ $\mu$ s, $V_{CC}$ = 30V $I_F$ =10A, di/dt = 200A/ $\mu$ s, $V_{CC}$ = 130V	T <sub>C</sub> = 25 °C T <sub>C</sub> = 25 °C	-	- -	35 45	ns ns
t <sub>a</sub> t <sub>b</sub> Q <sub>rr</sub>	$I_F = 10A$ , di/dt = 200A/ $\mu$ s, $V_{CC} = 130V$	$T_C = 25 ^{\circ}C$ $T_C = 25 ^{\circ}C$ $T_C = 25 ^{\circ}C$	- - -	15 12 36	- - -	ns ns nC
W <sub>AVL</sub>	Avalanche Energy (L = 20mH)		10	-	-	mJ

<sup>\*</sup> Pulse Test: Pulse Width=300 $\mu$ s, Duty Cycle=2%

### **Typical Performance Characteristics**

Figure 1. Typical Forward Voltage Drop



**Figure 2. Typical Reverse Current** 

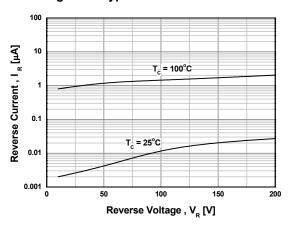


Figure 3. Typical Junction Capacitance

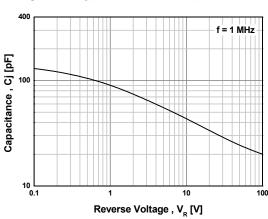


Figure 4. Typical Reverse Recovery Time

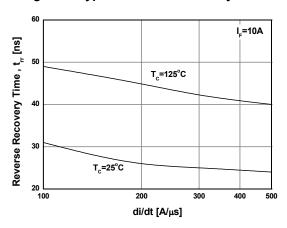
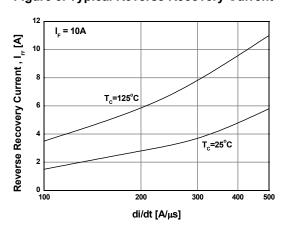
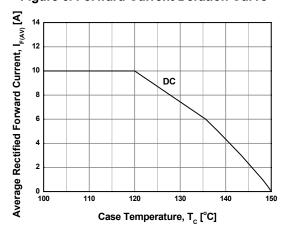


Figure 5. Typical Reverse Recovery Current

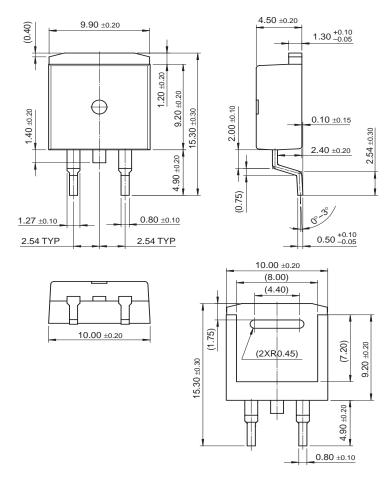


**Figure 6. Forward Current Deration Curve** 



### Package Demensions

## D<sup>2</sup>-PAK



Dimensions in Millimeters

Ultrafast Recovery Power Rectifier

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